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Epoxies for General Use with Piezoelectric Ceramics and Devices

What Epoxy can be used to Bond Piezo Ceramics and Devices?

APC is often asked this question by our customers. We would like to suggest the following as possible choices for evaluation. Please be advised that you must evaluate and test these epoxies in your application. APC makes no guarantee or warranty regarding the use of these epoxies.

General Bonding of Piezo Ceramic Crystals:

Loctite E-30CL: http://tds.loctite.com/tds5/docs/HYSAE-30CL-EN.PDF Possible Supplier: http://www.mcmaster.com/

- Epoxy in 50ml Adhesive Cartridge: # 6430A23

- Dispenser: # 74695A71

- Mixing Nozzles: # 74695A12

- Bond Thickness: Generally .0005" to .002"

General Bonding of Piezo Ceramic Crystals & Devices: (High Power & High Temp)

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Possible Supplier: www.freemansupply.com

- Epoxy in 50ml Adhesive Cartridge: # 056454

- Dispenser: # 056460

- Mixing Nozzles: # 056502

- Bond Thickness: Generally .002" to .005"

Note: While APC uses these epoxies for value added manufacturing of devices and sensors, other epoxies are available that will perform with similar results. APC recommends that you evaluate and test several epoxies in each application before deciding on which epoxy to use.

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